

SOT858-1

plastic thermal enhanced low profile land grid array package;
68 lands; resin based; body 10 x 15 x 1.3 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HLLGA68R
Package type industry code	HLLGA68R
Package style descriptive code	HLLGA (thermal enhanced low profile land grid array)
Package style suffix code	R (resin based)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-11-2007

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		9.9	-	10	10.1	mm
E	package width		14.9	-	15	15.1	mm
A	seated height		[tbd]	-	1.3	1.4	mm
A ₂	package height		[tbd]	-	1.3	[tbd]	mm
n ₂	actual quantity of termination		-	-	68	-	



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2. Package outline

HLLGA68R: plastic thermal enhanced low profile land grid array package;
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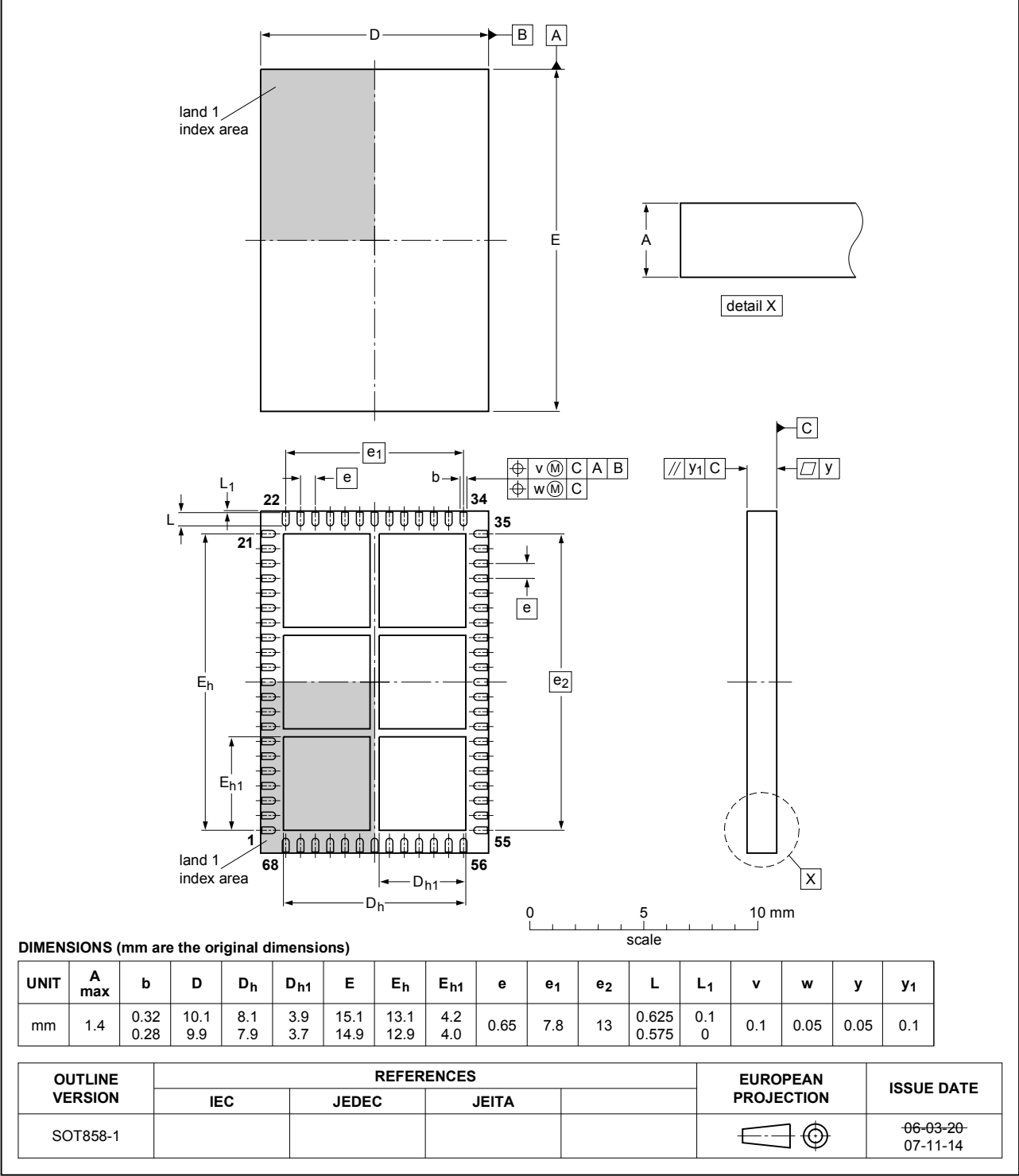


Fig. 1. Package outline HLLGA68R (SOT858-1)

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3. Soldering

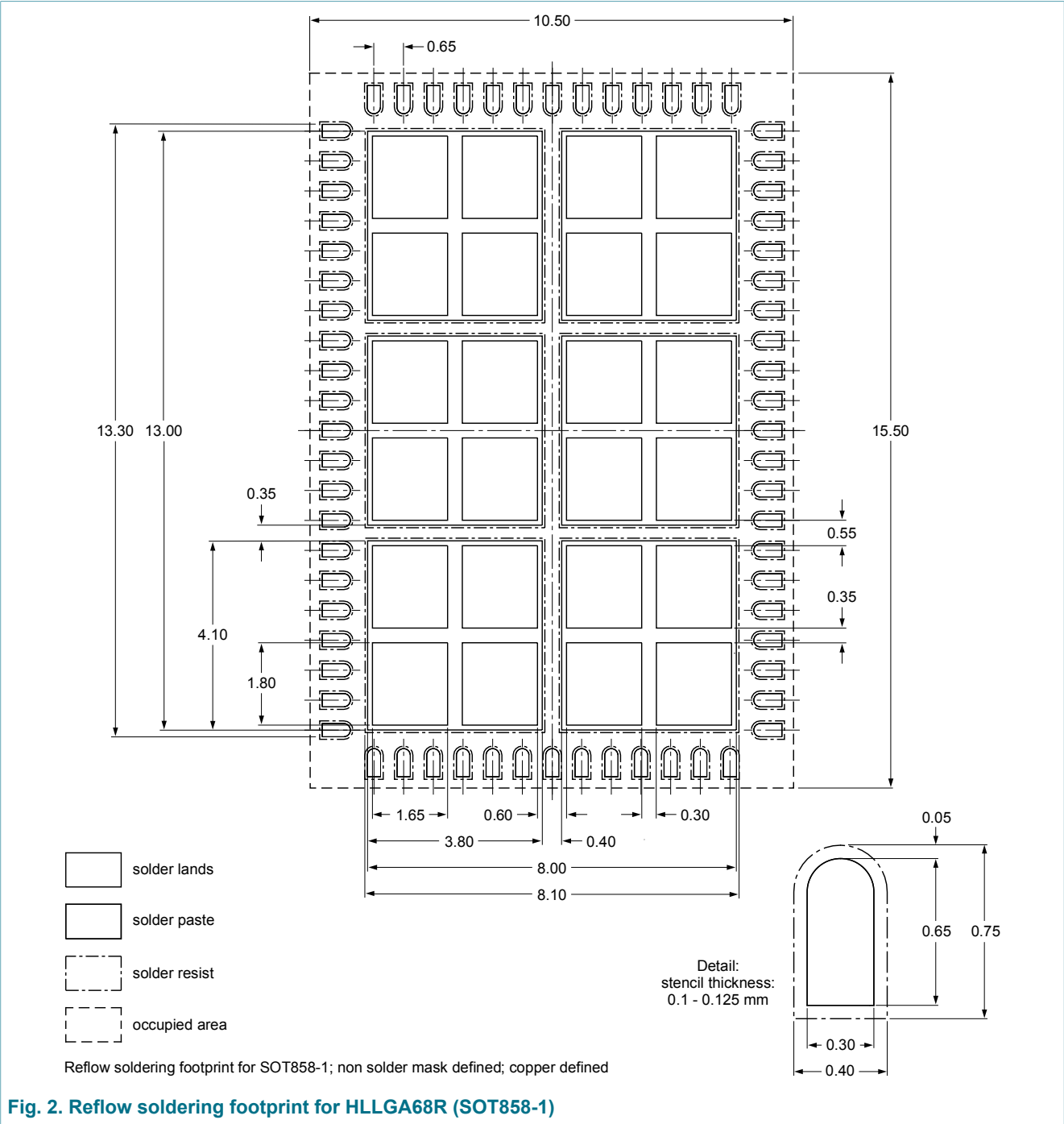


Fig. 2. Reflow soldering footprint for HLLGA68R (SOT858-1)

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4. Legal information

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